



# PMXB350UPE

20 V, P-channel Trench MOSFET

24 January 2014

Product data sheet

## 1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a leadless ultra small DFN1010D-3 (SOT1215) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

## 2. Features and benefits

- Trench MOSFET technology
- Leadless ultra small and ultra thin SMD plastic package:  $1.1 \times 1.0 \times 0.37$  mm
- Exposed drain pad for excellent thermal conduction
- ElectroStatic Discharge (ESD) protection 1 kV HBM
- Drain-source on-state resistance  $R_{DSon} = 350$  m $\Omega$

## 3. Applications

- High-side load switch and charging switch for portable devices
- Power management in battery driven portables
- LED driver
- DC-to-DC converter

## 4. Quick reference data

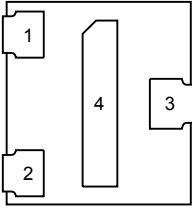
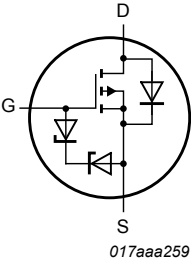
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$T_j = 25$ °C		-	-	-20	V
$V_{GS}$	gate-source voltage			-8	-	8	V
$I_D$	drain current	$V_{GS} = -4.5$ V; $T_{amb} = 25$ °C	[1]	-	-	-1.2	A
<b>Static characteristics</b>							
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = -4.5$ V; $I_D = -1.2$ A; $T_j = 25$ °C		-	350	447	m $\Omega$

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 <p>Transparent top view DFN1010D-3 (SOT1215)</p>	 <p>017aaa259</p>
2	S	source		
3	D	drain		
4	D	drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMXB350UPE	DFN1010D-3	DFN1010D-3: plastic thermal enhanced ultra thin small outline package; no leads; 3 terminals; body 1.1 x 1.0 x 0.37 mm	SOT1215

7. Marking

Table 4. Marking codes

Type number	Marking code
PMXB350UPE	11 10 00

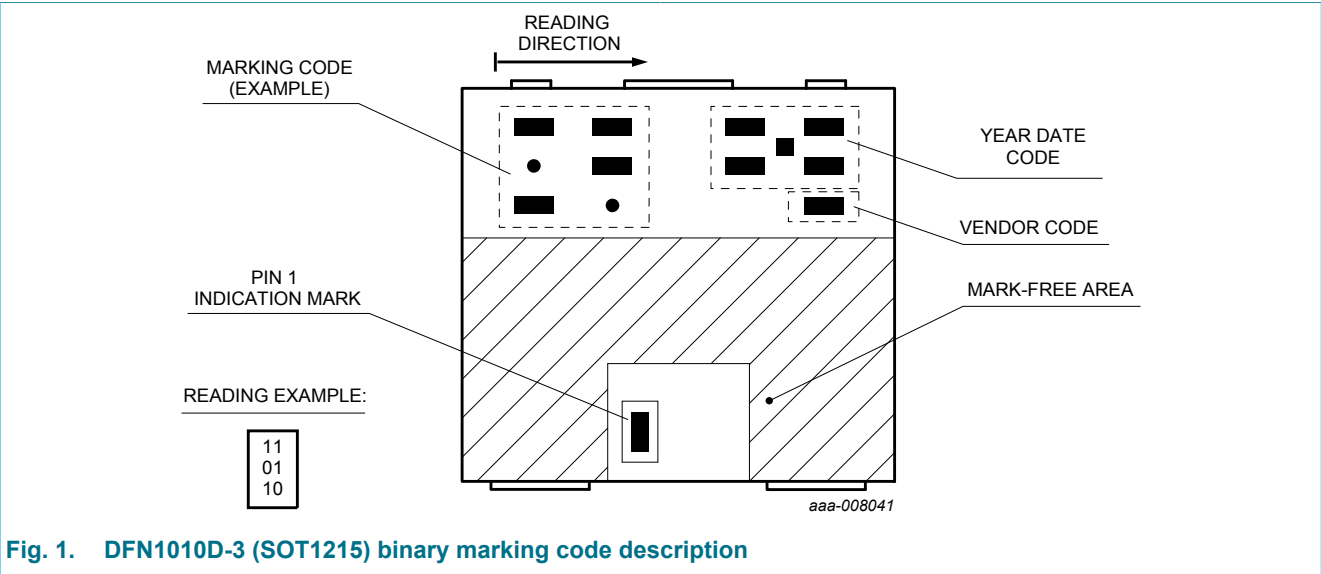


Fig. 1. DFN1010D-3 (SOT1215) binary marking code description

## 8. Limiting values

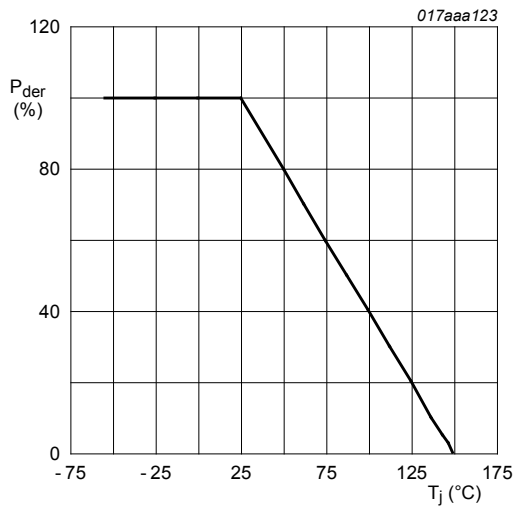
**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> = 25 °C		-	-20	V
V <sub>GS</sub>	gate-source voltage			-8	8	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 25 °C	[1]	-	-1.2	A
		V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 100 °C	[1]	-	-1	A
I <sub>DM</sub>	peak drain current	T <sub>amb</sub> = 25 °C; single pulse; t <sub>p</sub> ≤ 10 μs		-	-5	A
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C	[2]	-	360	mW
			[1]	-	930	mW
		T <sub>sp</sub> = 25 °C		-	5680	mW
T <sub>j</sub>	junction temperature			-55	150	°C
T <sub>amb</sub>	ambient temperature			-55	150	°C
T <sub>stg</sub>	storage temperature			-65	150	°C
<b>Source-drain diode</b>						
I <sub>S</sub>	source current	T <sub>amb</sub> = 25 °C	[1]	-	-0.9	A

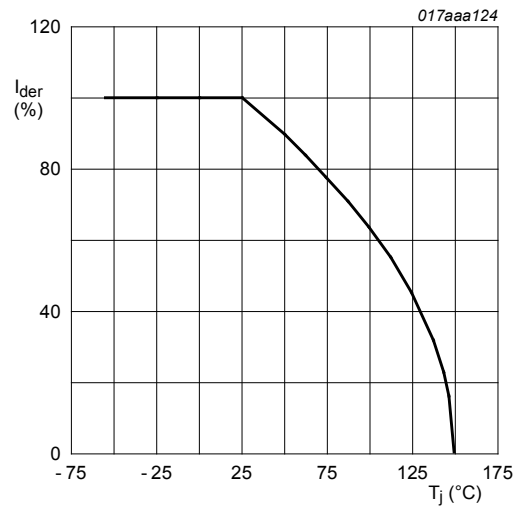
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.



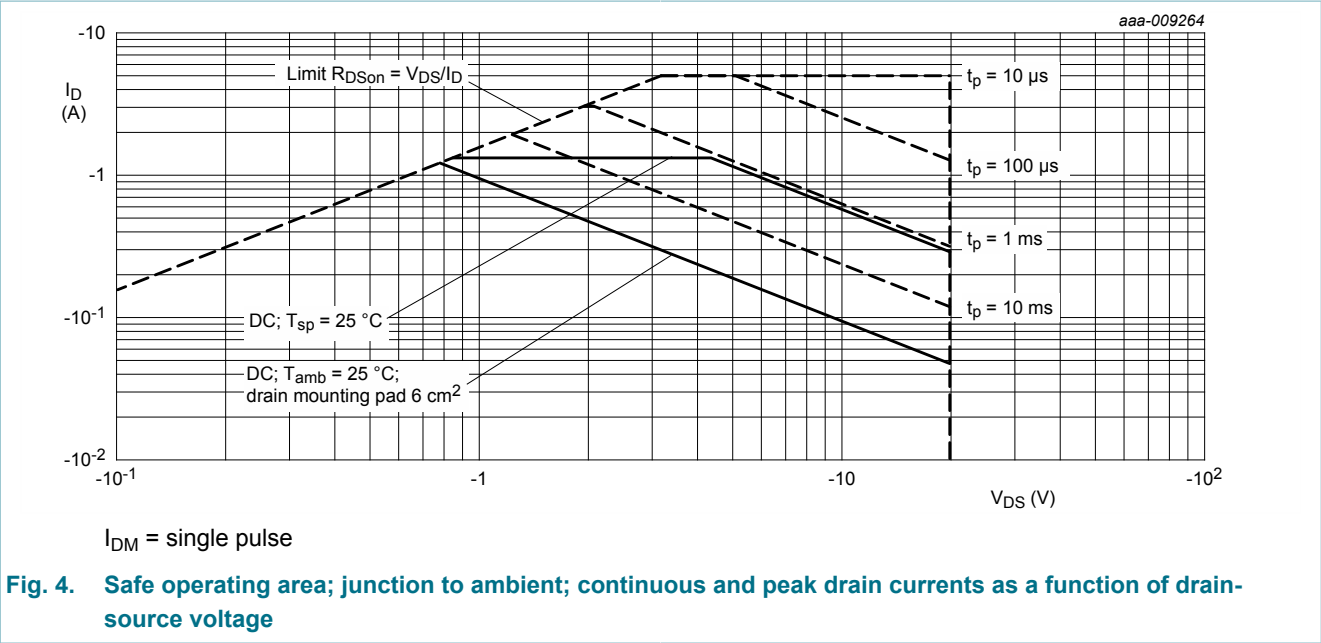
**Fig. 2. Normalized total power dissipation as a function of junction temperature**

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100 \%$$



**Fig. 3. Normalized continuous drain current as a function of junction temperature**

$$I_{der} = \frac{I_D}{I_{D(25^{\circ}\text{C})}} \times 100 \%$$



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	303	348	K/W
			[2]	-	116	134	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	17	22	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain  $6\ cm^2$ .

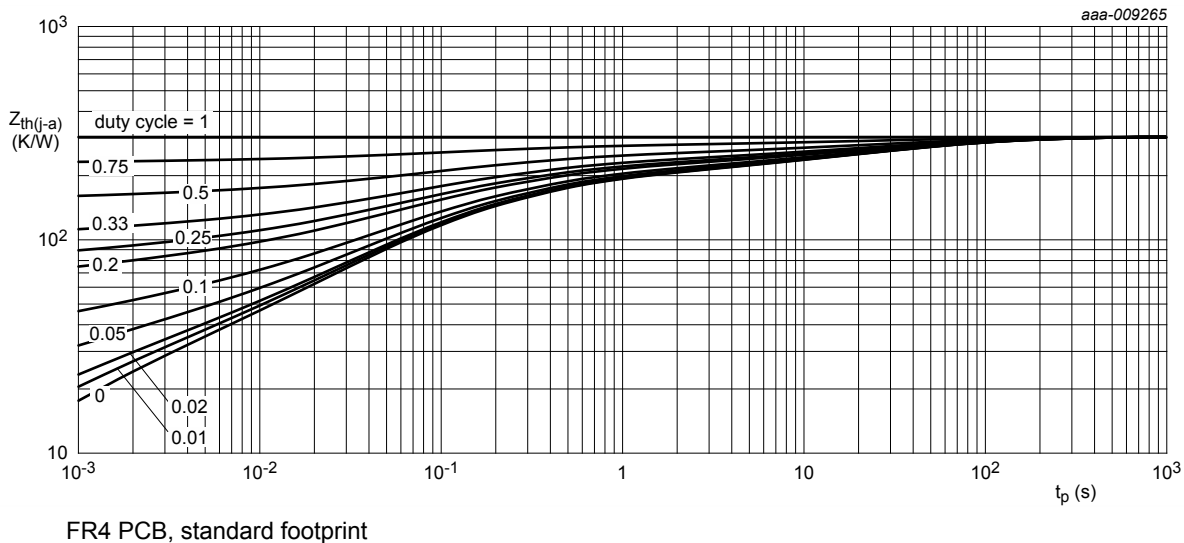


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

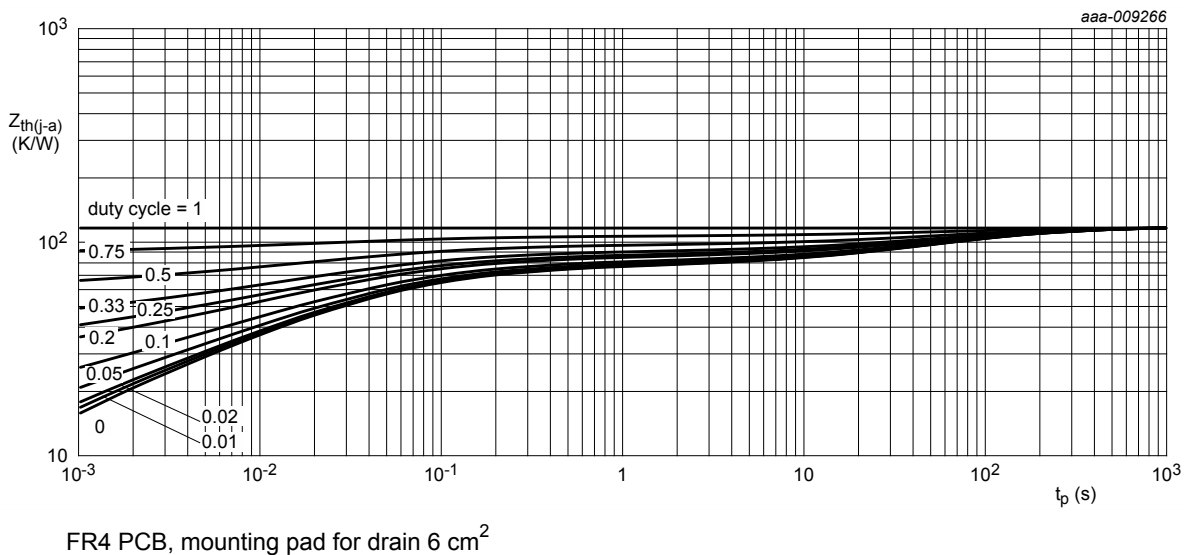


Fig. 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	I <sub>D</sub> = -250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-20	-	-	V
V <sub>GSth</sub>	gate-source threshold voltage	I <sub>D</sub> = -250 μA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 25 °C		-0.45	-0.7	-0.95	V
I <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = -20 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-	-1	μA
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = -8 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-	-10	μA
		V <sub>GS</sub> = 8 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-	10	μA
R <sub>DSon</sub>	drain-source on-state resistance	V <sub>GS</sub> = -4.5 V; I <sub>D</sub> = -1.2 A; T <sub>j</sub> = 25 °C		-	350	447	mΩ
		V <sub>GS</sub> = -4.5 V; I <sub>D</sub> = -1.2 A; T <sub>j</sub> = 150 °C		-	508	650	mΩ
		V <sub>GS</sub> = -2.5 V; I <sub>D</sub> = -1 A; T <sub>j</sub> = 25 °C		-	450	645	mΩ
		V <sub>GS</sub> = -1.8 V; I <sub>D</sub> = -0.4 A; T <sub>j</sub> = 25 °C		-	600	940	mΩ
		V <sub>GS</sub> = -1.5 V; I <sub>D</sub> = -10 mA; T <sub>j</sub> = 25 °C		-	760	2000	mΩ
		V <sub>GS</sub> = -1.2 V; I <sub>D</sub> = -1 mA; T <sub>j</sub> = 25 °C		-	1200	-	mΩ
g <sub>fs</sub>	forward transconductance	V <sub>DS</sub> = -5 V; I <sub>D</sub> = -1.2 A; T <sub>j</sub> = 25 °C		-	5.2	-	S
R <sub>G</sub>	gate resistance	f = 1 MHz		-	0.8	-	Ω
Dynamic characteristics							
Q <sub>G(tot)</sub>	total gate charge	V <sub>DS</sub> = -10 V; I <sub>D</sub> = -1.2 A; V <sub>GS</sub> = -4.5 V; T <sub>j</sub> = 25 °C		-	1.25	2.3	nC
Q <sub>GS</sub>	gate-source charge			-	0.27	-	nC
Q <sub>GD</sub>	gate-drain charge			-	0.28	-	nC
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = -10 V; f = 1 MHz; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	116	-	pF
C <sub>oss</sub>	output capacitance			-	16.5	-	pF
C <sub>rss</sub>	reverse transfer capacitance			-	12.2	-	pF
t <sub>d(on)</sub>	turn-on delay time	V <sub>DS</sub> = -10 V; I <sub>D</sub> = -1.2 A; V <sub>GS</sub> = -4.5 V; R <sub>G(ext)</sub> = 6 Ω; T <sub>j</sub> = 25 °C		-	3	-	ns
t <sub>r</sub>	rise time			-	9	-	ns
t <sub>d(off)</sub>	turn-off delay time			-	18	-	ns
t <sub>f</sub>	fall time			-	6	-	ns
Source-drain diode							
V <sub>SD</sub>	source-drain voltage	I <sub>S</sub> = -0.9 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		-	-0.8	-1.2	V

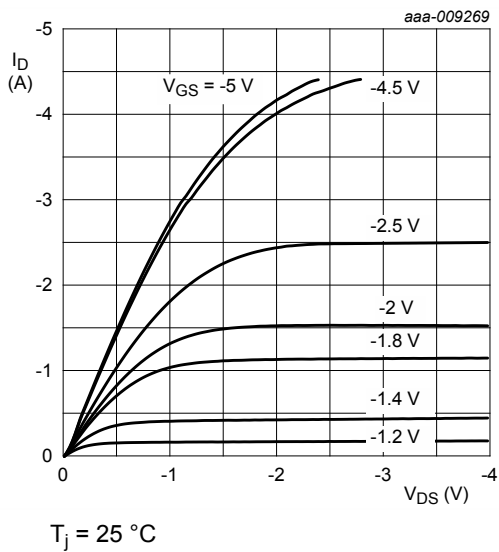


Fig. 7. Output characteristics: drain current as a function of drain-source voltage; typical values

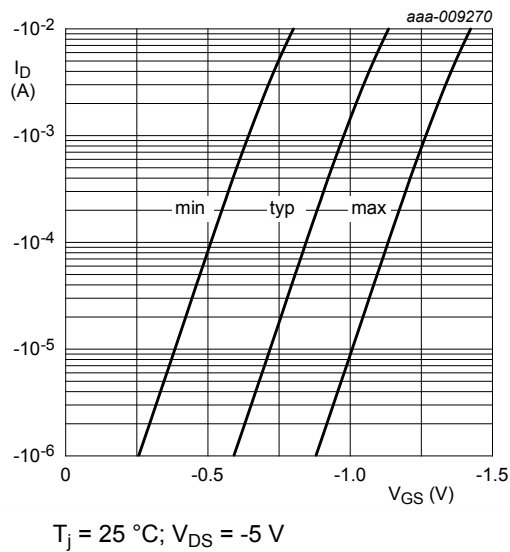


Fig. 8. Sub-threshold drain current as a function of gate-source voltage

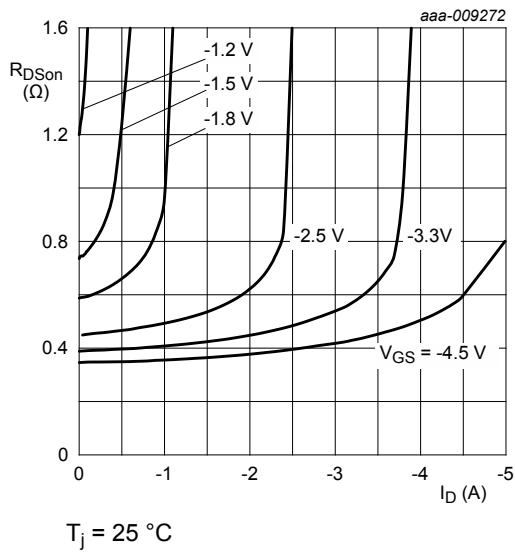


Fig. 9. Drain-source on-state resistance as a function of drain current; typical values

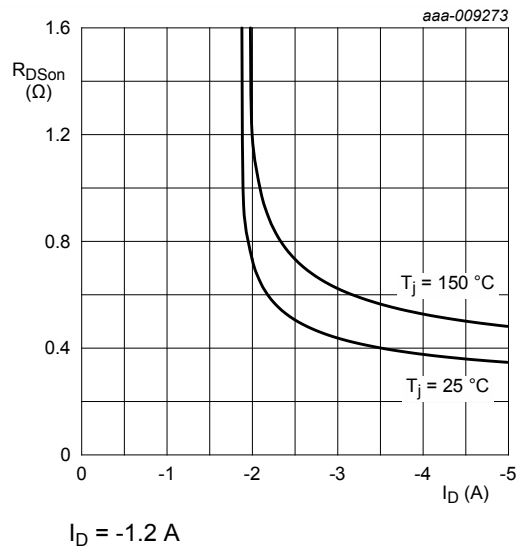


Fig. 10. Drain-source on-state resistance as a function of gate-source voltage; typical values

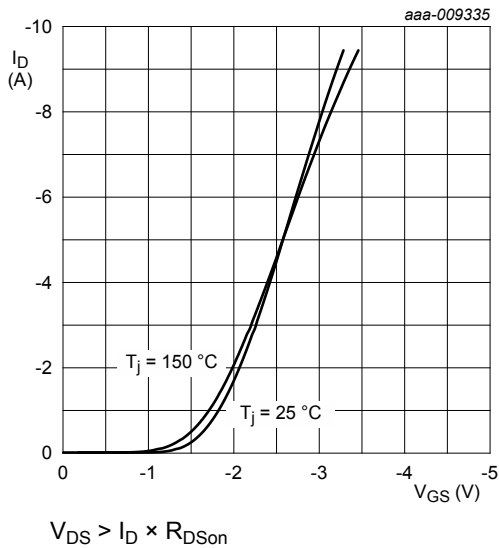


Fig. 11. Transfer characteristics: drain current as a function of gate-source voltage; typical values

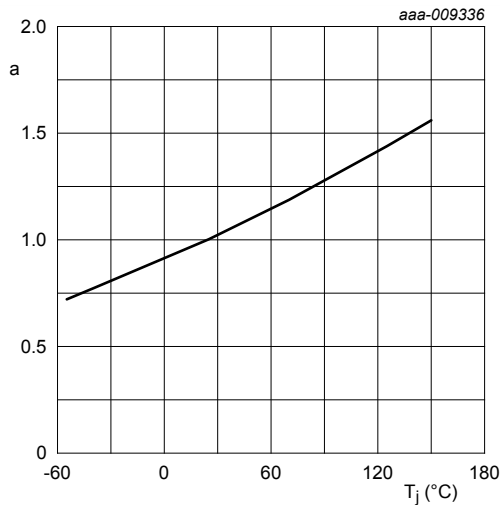


Fig. 12. Normalized drain-source on-state resistance as a function of junction temperature; typical values

$$a = \frac{R_{DS(on)}}{R_{DS(on)(25\text{ °C})}}$$

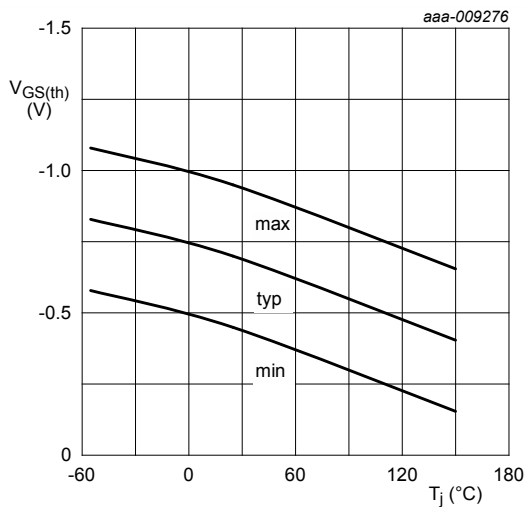


Fig. 13. Gate-source threshold voltage as a function of junction temperature

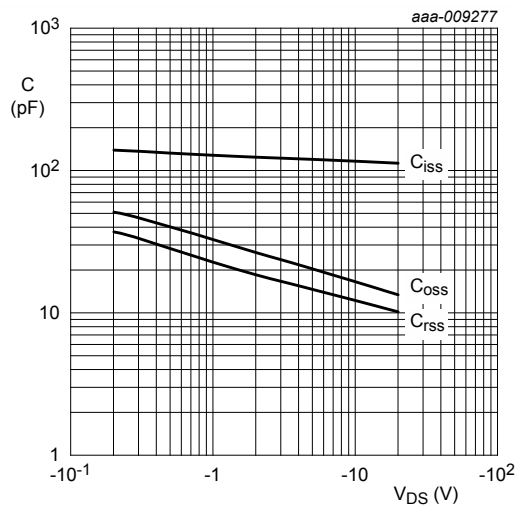


Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



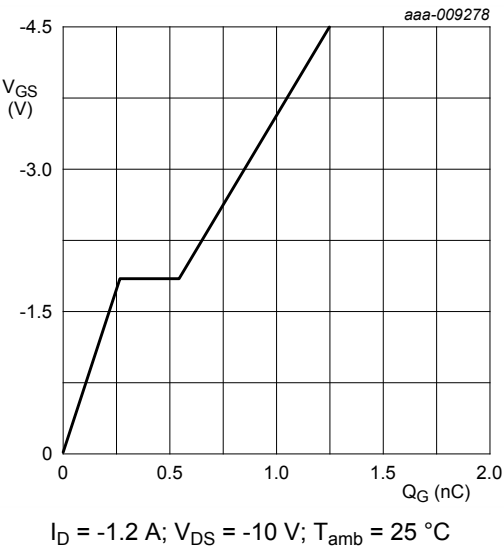


Fig. 15. Gate-source voltage as a function of gate charge; typical values

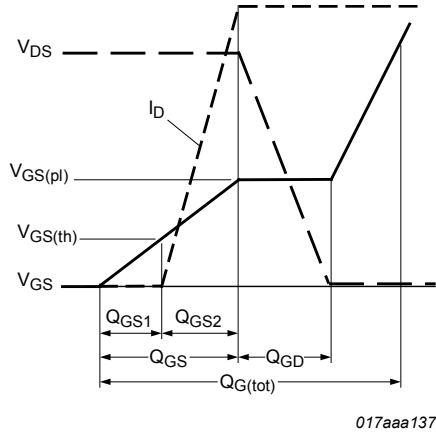


Fig. 16. MOSFET transistor: Gate charge waveform definitions

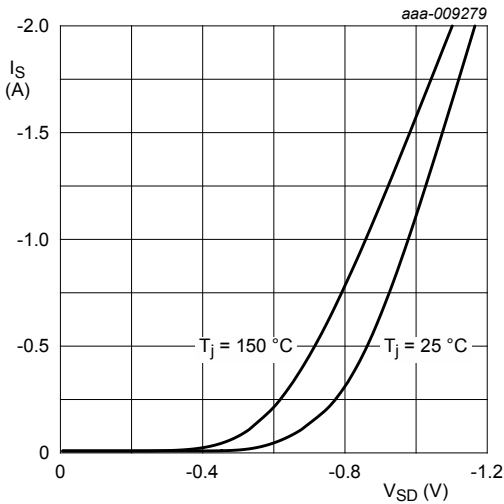


Fig. 17. Source current as a function of source-drain voltage; typical values

## 11. Test information

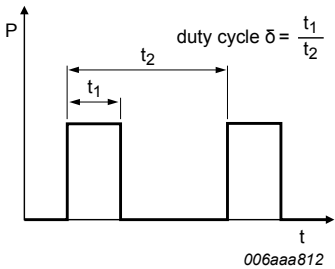
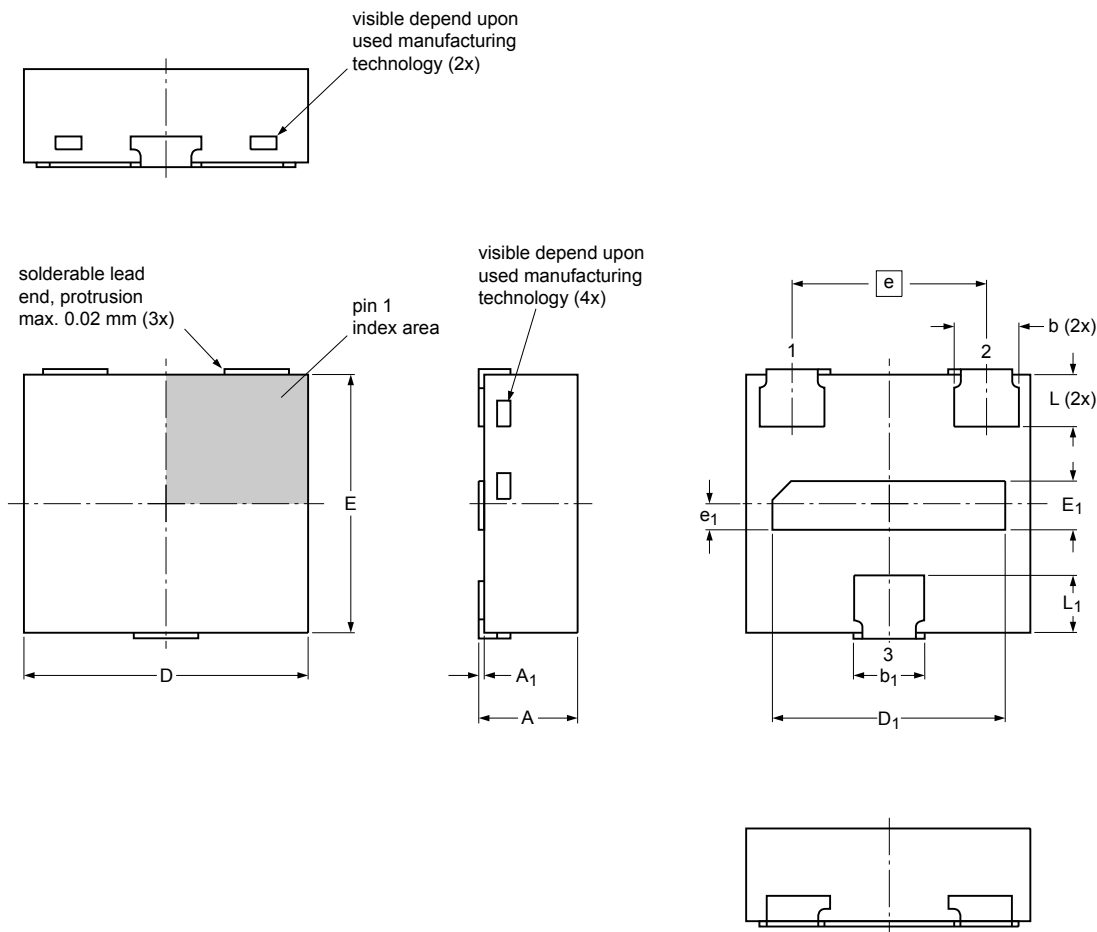


Fig. 18. Duty cycle definition

12. Package outline

DFN1010D-3: plastic thermal enhanced ultra thin small outline package; no leads; 3 terminals; body: 1.1 x 1.0 x 0.37 mm SOT1215



0 1 mm  
scale

Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	b	b <sub>1</sub>	D	D <sub>1</sub>	E	E <sub>1</sub>	e	e <sub>1</sub>	L	L <sub>1</sub>
min	0.34		0.22	0.245	1.05	0.87	0.95	0.16			0.17	0.195
mm	nom		0.25	0.275	1.10	0.90	1.00	0.19	0.75	0.1	0.20	0.225
	max	0.40	0.04	0.30	0.325	1.15	0.95	1.05	0.24		0.25	0.275

Note  
1. Dimension A is including plating thickness.

sot1215\_po

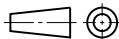
Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1215						13-03-05 13-03-06

Fig. 19. Package outline DFN1010D-3 (SOT1215)

13. Soldering

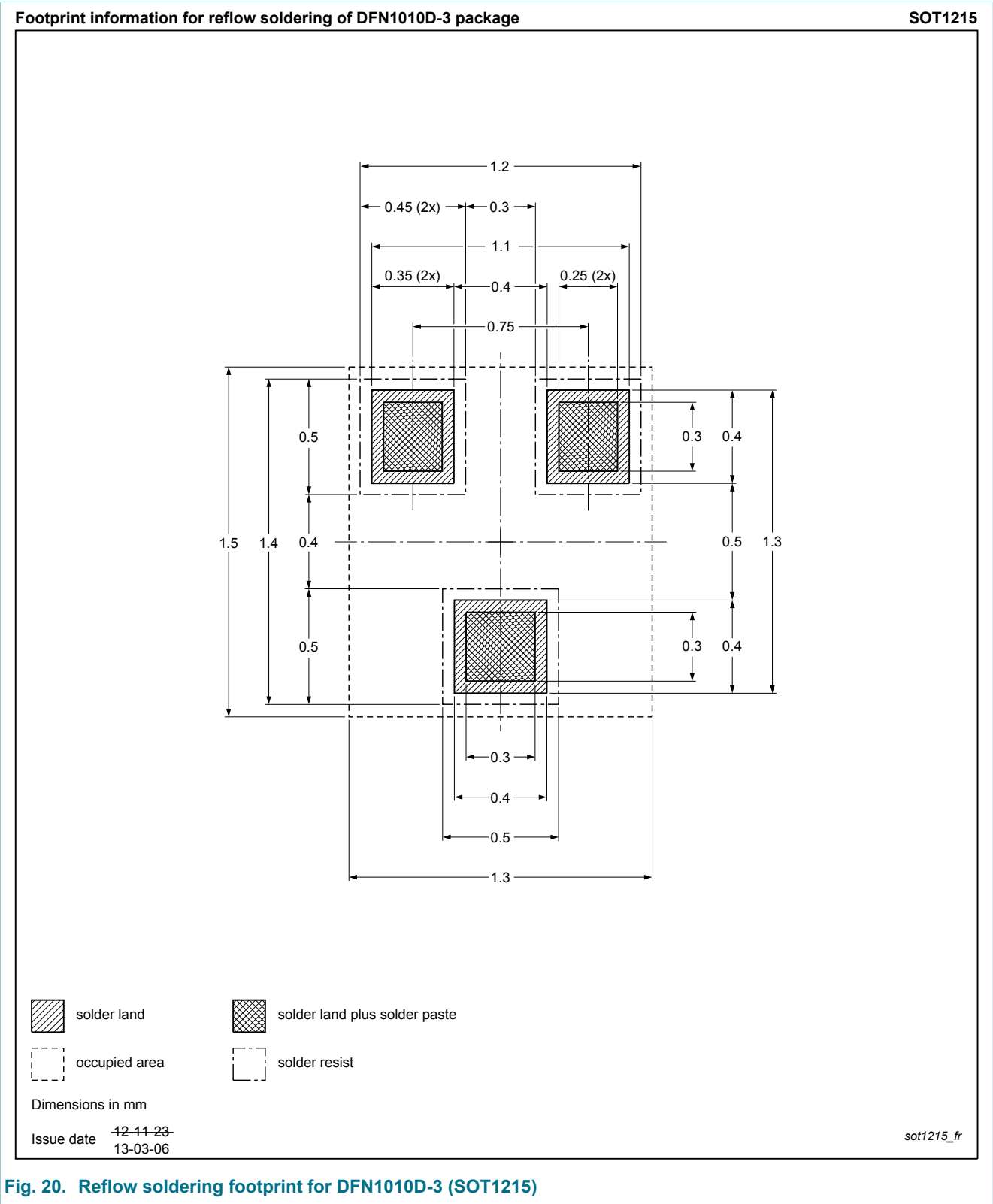


Fig. 20. Reflow soldering footprint for DFN1010D-3 (SOT1215)

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMXB350UPE v.2	20140124	Product data sheet	-	PMXB350UPE v.1
Modifications:	<ul style="list-style-type: none"><li>Editorial update</li></ul>			
PMXB350UPE v.1	20130919	Product data sheet	-	-

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### 15.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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